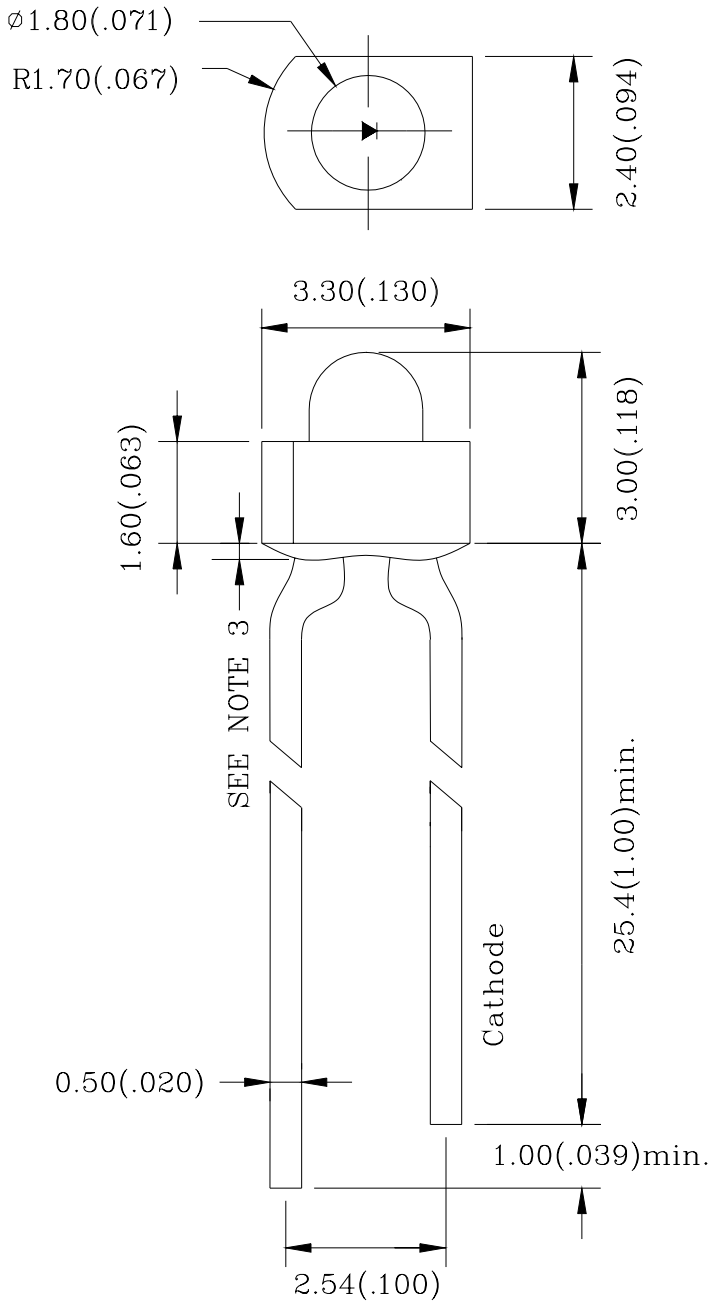


PACKAGE DIMENSIONS



- Note:
- 1.All Dimensions are in millimeters.
 - 2.Tolerance is $\pm 0.25\text{mm}(0.010\text{ ''})$ Unless otherwise specified.
 - 3.Protruded resin under flange is $1.5\text{mm}(0.059\text{ ''})$ max.
 - 4.Lead spacing is measured where the leads emerge from the package.
 - 5.Specification are subject to change without notice



1.8 mm DIA LED LAMP

HH-1.8YD-50

REV:A/1

FEATURES

- * 1.8 mm DIA TOWER TYPE LED LAMP
- * HIGH LUMINOUS INTENSITY OUTPUT.
- * LOW POWER CONSUMPTION.
- * HIGH EFFICIENCY.
- * VERSATILE MOUNTING ON P.C. BOARD OR PANEL.
- * I.C. COMPATIBLE.

CHIP MATERIALS

- * Dice Material : GaAlInP/GaAs
- * Light Color : ULTRA YELLOW
- * Lens Color : YELLOW DIFFUSED

ABSOLUTE MAXIMUM RATING : (Ta = 25°C)

| SYMBOL | PARAMETER | ULTRA YELLOW | UNIT |
|--------|---|---------------|-------|
| PAD | Power Dissipation Per Chip | 80 | mW |
| VR | Reverse Voltage Per Chip | 5 | V |
| IAF | Continuous Forward Current Per Chip | 30 | mA |
| IPF | Peak Forward Current Per Chip (Duty – 0.1,1KHz) | 120 | mA |
| — | Derating Linear From 25°C Per Chip | 0.40 | mA/°C |
| Topr | Operating Temperature Range | -25°C to 85°C | |
| Tstg | Storage Temperature Range | -40°C to 85°C | |

Lead Soldering Temperature { 1.6mm(0.063 inch) From Body } 260°C ± 5°C for 5 Seconds

ELECTRO-OPTICAL CHARACTERISTICS : (Ta = 25°C)

| SYMBOL | PARAMETER | TEST CONDITION | MIN. | TYP. | MAX. | UNIT |
|--------|--------------------------|----------------|------|------|------|------|
| VF | Forward Voltage | IF = 20mA | | 2.0 | | V |
| IR | Reverse Current | VR = 5V | | | 100 | μA |
| λD | Dominant Wavelength | IF = 20mA | | 590 | | nm |
| Δλ | Spectral Line Half-Width | IF = 20mA | | 15 | | nm |
| 2θ1/2 | Half Intensity Angle | IF = 20mA | | 50 | | deg |
| IV | Luminous Intensity | IF = 20mA | | 900 | | mcd |

